

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|---------|---|---|------------------|---------|------------------|
| L1 | 6 | ((("20030102566") or ("20040043607") or ("6903443"))). PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/06 17:40 |
| L2 | 3325 | ((438/761) or (438/667) or (438/637) or (438/640)).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/06 18:19 |
| S1 | 1 | US-6251488-\$.DID. OR US-US6259962-\$.DID. OR US-US6268584-\$.DID. OR US-US639251-\$.DID. | USPAT | OR | OFF | 2004/08/04 19:44 |
| S2 | 4 | US-6251488-\$.DID. OR US-6259962-\$.DID. OR US-6268584-\$.DID. OR US-6391251-\$.DID. | USPAT | OR | OFF | 2004/08/04 20:09 |
| S3 | 0 | 20020171777-\$.DID. OR 20030151167-\$.DID. | US-PGPUB; USPAT | OR | OFF | 2004/08/04 20:10 |
| S4 | 2 | "20020171777".pn. OR "20030151167".pn. | US-PGPUB; USPAT | OR | OFF | 2004/08/04 20:11 |
| S5 | 2 | "20020171177".pn. OR "20030151167".pn. | US-PGPUB; USPAT | OR | OFF | 2004/08/04 20:16 |
| S6 | 506959 | throughhole or through adj hole or via adj hole or viahole | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:02 |
| S7 | 3018261 | photopolymer or polymer or resin or epoxy | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:45 |
| S8 | 33758 | laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:49 |
| S9 | 103 | (throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/04 20:19 |

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| S10 | 103 | ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4))) and (@ad < "20030916")) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/04 20:19 |
| S11 | 25 | (throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) same (photopolymer or polymer or resin or epoxy) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/04 20:20 |
| S12 | 13 | (throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near8 (photopolymer or polymer or resin or epoxy) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/04 20:34 |
| S13 | 0 | ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near8 (photopolymer or polymer or resin or epoxy)) not ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) same (photopolymer or polymer or resin or epoxy)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/04 20:35 |
| S14 | 12 | ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) same (photopolymer or polymer or resin or epoxy)) not ((throughhole or through adj hole or via adj hole or viahole) same (laser near4 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near8 (photopolymer or polymer or resin or epoxy)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/04 20:35 |
| S15 | 3022763 | substrate or wafer or die or chip or ic | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:57 |
| S16 | 507324 | throughhole or through adj hole or via adj hole or viahole | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:52 |

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| S17 | 0 | trepn\$4 same (throughhole or through adj hole or via adj hole or viahole) same (substrate or wafer or die or chip or ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:37 |
| S18 | 0 | trepn\$4 and (throughhole or through adj hole or via adj hole or viahole) and (substrate or wafer or die or chip or ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:37 |
| S19 | 0 | trepn\$4 and (throughhole or through adj hole or via adj hole or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:34 |
| S20 | 1617 | trepn\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:02 |
| S21 | 2 | trepn\$4 and (substrate or wafer or die or chip or ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:35 |
| S22 | 14 | trepn\$4 same (throughhole or through adj hole or via adj hole or viahole) same (substrate or wafer or die or chip or ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:37 |
| S23 | 3140914 | photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:49 |
| S24 | 4719 | (throughhole or through adj hole or via adj hole or viahole) near2 (photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:49 |
| S25 | 3938724 | cur\$4 or harden\$4 or consolidat\$4 or ossif\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:49 |
| S26 | 210824 | (photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:50 |

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| S27 | 965 | ((throughhole or through adj hole or via adj hole or viahole) near2 (photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4))) and ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:55 |
| S28 | 2421605 | edge or border or perimeter or circumference | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:52 |
| S29 | 4636315 | throughhole or through adj hole or via adj hole or viahole or open\$4 or recess or aperature | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:03 |
| S30 | 86 | (throughhole or through adj hole or via adj hole or viahole or open\$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near4 (edge or border or perimeter or circumference) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:56 |
| S31 | 27 | ((throughhole or through adj hole or via adj hole or viahole or open\$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near4 (edge or border or perimeter or circumference)) and (substrate or wafer or die or chip or ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:57 |
| S32 | 3022763 | substrate or wafer or die or chip or ic | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 14:57 |

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|-----|---------|---|---|----|----|------------------|
| S33 | 27 | ((throughhole or through adj hole or via adj hole or viahole or open\$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near4 (edge or border or perimeter or circumference)) and (substrate or wafer or die or chip or ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:03 |
| S34 | 178 | (throughhole or through adj hole or via adj hole or viahole or open\$4 or recess or aperature) same ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) same (drill\$4 or etch\$4 or laser\$4) near4 (throughhole or through adj hole or via adj hole or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:06 |
| S35 | 6715023 | coat\$4 or lin\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:07 |
| S36 | 505 | (throughhole or through adj hole or via adj hole or viahole) near4 (coat\$4 or lin\$4) near4 (photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:09 |
| S37 | 369 | (throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near4 (photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:13 |

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| S38 | 193 | (throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near4 (photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) and (substrate or wafer or die or chip or ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:11 |
| S39 | 193 | (throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near4 (photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) and (substrate or wafer or die or chip or ic) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:12 |
| S40 | 24 | (throughhole or through adj hole or via adj hole or viahole) near4 ((photopolymer or polymer or resin or epoxy or thermoset\$4 or thermoplastic\$4 or thermo adj (set\$6 or plastic\$4)) near2 (cur\$4 or harden\$4 or consolidat\$4 or ossif\$4)) near4 (coat\$4 or lin\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 15:14 |
| S41 | 1617 | trepan\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:02 |
| S42 | 336075 | drill\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:02 |
| S43 | 507324 | throughhole or through adj hole or via adj hole or viahole | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:03 |
| S44 | 3503714 | metal or copper or cvd | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:04 |

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| S45 | 120667 | cvd | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:04 |
| S46 | 0 | trepan\$4 near8 drill\$4 same cvd near4 (metal or copper or cvd) near8 (throughhole or through adj hole or via adj hole or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:05 |
| S47 | 0 | trepan\$4 near8 drill\$4 same cvd near8 (throughhole or through adj hole or via adj hole or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:05 |
| S48 | 0 | trepan\$4 near8 drill\$4 and cvd near8 (throughhole or through adj hole or via adj hole or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:05 |
| S49 | 0 | trepan\$4 same drill\$4 and cvd near8 (throughhole or through adj hole or via adj hole or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:05 |
| S50 | 454 | trepan\$4 same drill\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:05 |
| S51 | 22 | trepan\$4 same drill\$4 same (throughhole or through adj hole or via adj hole or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:16 |
| S52 | 30778 | frustoconical | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:16 |
| S53 | 304 | frustoconical.ti. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2004/08/05 17:16 |
| S54 | 2777 | ((438/761) or (438/667) or (438/637) or (438/640)).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/06 18:19 |
| S55 | 0 | "200400112881".pn. and plat\$4 | USPAT | OR | ON | 2004/08/05 19:46 |

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| S56 | 0 | "200400112881".pn. | USPAT | OR | ON | 2004/08/05 19:46 |
| S57 | 0 | "200400112881".pn. | US-PGPUB; USPAT | OR | ON | 2004/08/05 19:47 |
| S58 | 1 | "20040112881".pn. | US-PGPUB; USPAT | OR | ON | 2004/08/05 19:47 |
| S59 | 1 | "20040112881".pn. and plat\$4 | US-PGPUB; USPAT | OR | ON | 2004/08/05 19:47 |